



N-Channel 20 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | |
|---------------------|----------------------------------|------------------|-----------------------|--|
| V _{DS} (V) | $R_{DS(on)}(\Omega)$ $I_D(A)$ | | Q _g (Typ.) | |
| | 0.049 at V _{GS} = 4.5 V | 6.1 ^a | | |
| 20 | 0.056 at V _{GS} = 2.5 V | 5.7 | 6.0 | |
| | 0.065 at V _{GS} = 1.8 V | 5.3 | | |

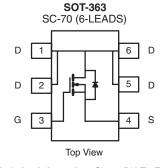
FEATURES

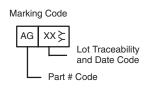
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

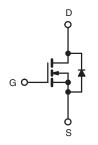


APPLICATIONS

· Load Switch for Portable Devices







Ordering Information: Si1488DH-T1-E3 (Lead (Pb)-free) Si1488DH-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

| Parameter | | Symbol | Limit | Unit | |
|---|-----------------------------------|-----------------|---------------------|------|--|
| Drain-Source Voltage | | V _{DS} | 20 | ., | |
| Gate-Source Voltage | | V _{GS} | ± 8 | V | |
| Continuous Drain Current (T _J = 150 °C) ^a | T _C = 25 °C | | 6.1 | | |
| | T _C = 70 °C | | 4.9 | | |
| | T _A = 25 °C | I _D | 4.6 ^{b, c} | | |
| | T _A = 70 °C | | 3.7 ^{b, c} | Α | |
| Pulsed Drain Current | | I _{DM} | 20 | | |
| Avalanche Current | | I _{AS} | 10 | | |
| Repetitive Avalanche Energy | L = 0.1 mH | | 5 | mJ | |
| Continuous Courses Brain Binds Coursest | T _C = 25 °C | | 2.3 | | |
| Continuous Source-Drain Diode Current | T _A = 25 °C | I _S | 1.3 ^{b, c} | A | |
| | T _C = 25 °C | | 2.8 | | |
| Maximum Power Dissipation ^a | T _C = 70 °C | | 1.8 | 10/ | |
| | T _A = 25 °C | P _D | 1.5 ^{b, c} | W | |
| | T _A = 70 °C | | 1.0 ^{b, c} | | |
| Operating Junction and Storage Temperature Ra | T _J , T _{stq} | - 55 to 150 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|---|--------------|-------------------|---------|---------|----------|--|
| Parameter | | Symbol | Typical | Maximum | Unit | |
| Maximum Junction-to-Ambient ^{b, d} | t ≤ 5 s | R _{thJA} | 60 | 80 | °C/W | |
| Maximum Junction-to-Foot (Drain) | Steady State | R _{thJF} | 34 | 45 | J - C/VV | |

Notes

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- $c. \quad t=5 \ s.$
- d. Maximum under steady state conditions is 125 °C/W.

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| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|---|-----------------------|---|------|--------|-------|-------|--|
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$ | 20 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | т. | | 20.2 | | 1400 | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}$ | I _D = 250 μA | | - 2.75 | | mV/°C | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | 0.45 | | 0.95 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$ | | | ± 100 | nA | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 20 V, V _{GS} = 0 V | | | 1 | μΑ | |
| | | V _{DS} = 20 V, V _{GS} = 0 V, T _J = 85 °C | | | 10 | μΑ | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$ | 20 | | | Α | |
| | | $V_{GS} = 4.5 \text{ V}, I_D = 4.6 \text{ A}$ | | 0.041 | 0.049 | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 2.5 \text{ V}, I_D = 4.3 \text{ A}$ | | 0.047 | 0.056 | Ω | |
| | | V _{GS} = 1.8 V, I _D = 3.9 A | | 0.054 | 0.065 | 1 | |
| Forward Transconductance | 9 _{fs} | V _{DS} = 10 V, I _D = 4.6 A | | 15 | | mS | |
| Dynamic ^b | • | | • | | | • | |
| Input Capacitance | C _{iss} | | | 530 | | | |
| Output Capacitance | C _{oss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | | 100 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 48 | | 1 | |
| Total Cata Chausa | | $V_{DS} = 10 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 4.6 \text{ A}$ | | 6.6 | 10 | | |
| Total Gate Charge | Qg | | | 6 | 9 | pC | |
| Gate-Source Charge | Q _{gs} | $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 4.6 \text{ A}$ | | 1.5 | | | |
| Gate-Drain Charge | Q_{gd} | | | 0.9 | | | |
| Gate Resistance | R_{g} | f = 1 MHz | | 7.3 | 11 | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 8.5 | 13 | | |
| Rise Time | t _r | $V_{DD} = 10 \text{ V, R}_{I} = 2.7 \Omega$ | | 45 | 68 | - ns | |
| Turn-Off DelayTime | t _{d(off)} | $I_D \cong 3.7 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$ | | 35 | 53 | | |
| Fall Time | t _f | | | 82 | 123 | | |
| Drain-Source Body Diode Characteristic | cs | | | | l . | | |
| Continous Source-Drain Diode Current | I _S | T _C = 25 °C | | | 2.3 | _ | |
| Pulse Diode Forward Current ^a | I _{SM} | | | | 20 | A | |
| Body Diode Voltage | V_{SD} | I _S = 2.2 A | | 0.8 | 1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 10.6 | 16 | nC | |
| Body Diode Reverse Recovery Charge | Q _{rr} | 1 000 4 41/45 400 4/55 | | 3.7 | 5.7 | ns | |
| Reverse Recovery Fall Time | t _a | I _F = 3.2 A, dl/dt = 100 A/μs | | 6.2 | | | |
| Reverse Recovery Rise Time | t _b | 1 | | 4.4 | | | |

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

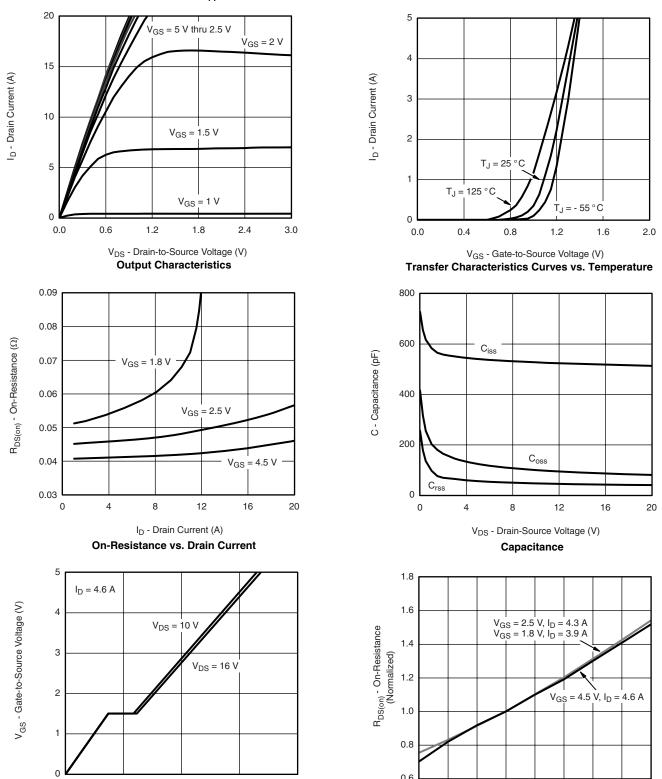
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



0

Q_g - Total Gate Charge (nC)

Gate Charge

125

- 25

- 50

25

50

 T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

75

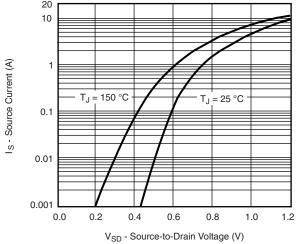
100

150

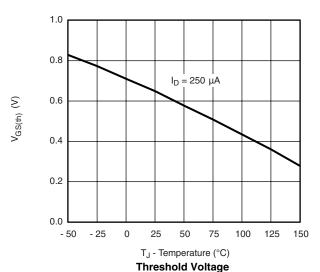
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TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

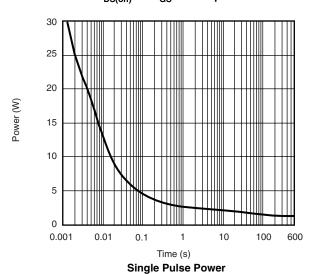


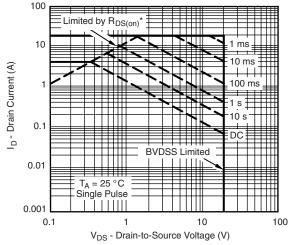
Source-Drain Diode Forward Voltage



0.12 0.09 0.09 0.06 0.06 T_A = 125 °C T_A = 25 °C

 V_{GS} - Gate-to-Source Voltage (V) $\mathbf{R}_{DS(on)}$ vs. V_{GS} vs. Temperature





* $V_{GS} > \mbox{minimum } V_{GS}$ at which $R_{DS(on)}$ is specified

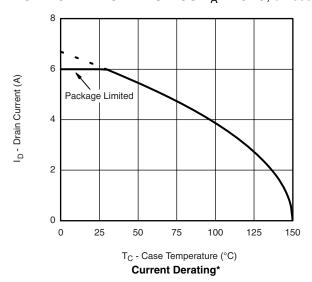
Safe Operating Area, Junction-to-Ambient

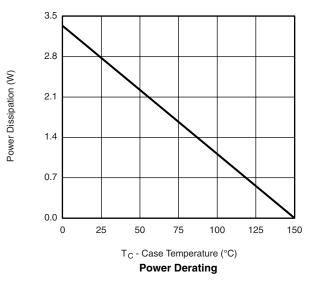






TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



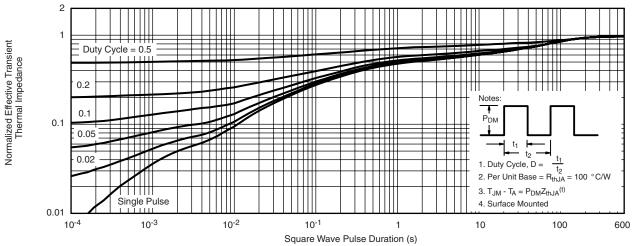


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

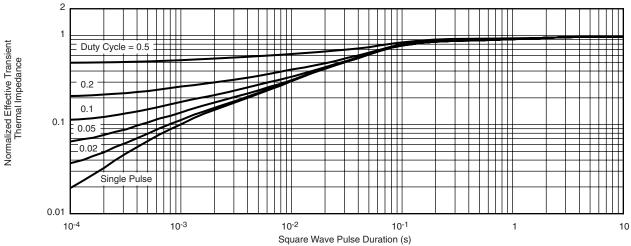
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TYPICAL CHARACTERISTICS $T_A = 25 \, ^{\circ}C$, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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